

# Low VF SMD Schottky Barrier Diode

#### **FEATURES**

- Low power loss, high current capability, low VF
- Surface mount device type
- Moisture sensitivity level (MSL): 1
- Packing code with suffix "G" means green compound (halogen-free)





**SOD-323F** 



#### MECHANICAL DATA

- Case : Flat lead SOD-323F small outline plastic package
- Molding compound, UL flammability classification rating 94V-0
- Terminal: Matte tin plated, lead free,
- solderable per MIL-STD-202, Method 208 guaranteed
- High temperature soldering guaranteed :  $260^{\circ}\text{C}/10\text{s}$
- Polarity: Indicated by cathode band
- Weight: 4.6 ± 0.5 mgMarking Code: S8



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T <sub>A</sub> =25℃ unless otherwise noted)					
PARAMETER		SYMBOL	VALUE	UNIT	
Power Dissipation		$P_{D}$	200	mW	
Repetitive Peak Reverse Voltage		$V_{RRM}$	40	V	
Reverse Voltage		$V_R$	30	V	
Mean Forward Current		Io	30	mA	
Non-Repetitive Peak Forward Surge Current	60Hz for 1 Cyc.	I <sub>FSM</sub>	0.2	Α	
Thermal Resistance (Junction to Ambient)	(Note)	$R_{\theta JA}$	500	°C/W	
Junction and Storage Temperature Range	_	$T_J,T_STG$	-40 to +125	°C	

	PARAMETER	SYMBOL	TYP	MAX	UNIT
Forward Voltage	I <sub>F</sub> = 1 mA	$V_{F}$	-	0.37	V
Reverse Leakage Current	V <sub>R</sub> = 30 V	$I_R$	-	0.5	μΑ
Junction Capacitance	$V_R = 1V$ , $f = 1.0 MHz$	$C_J$	2	-	pF

Note: Valid provided that electrodes are kept at ambient temeprature.



#### RATINGS AND CHARACTERISTICS CURVES

(T<sub>A</sub>=25°C unless otherwise noted)

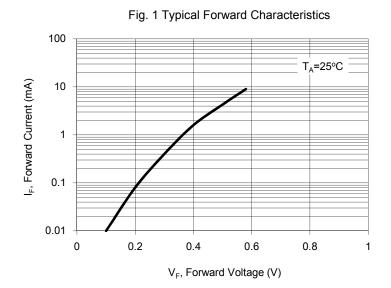
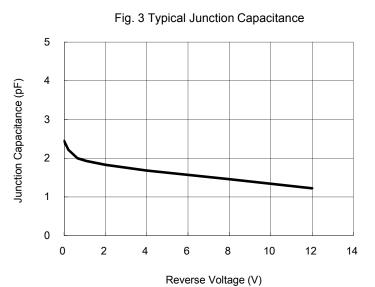
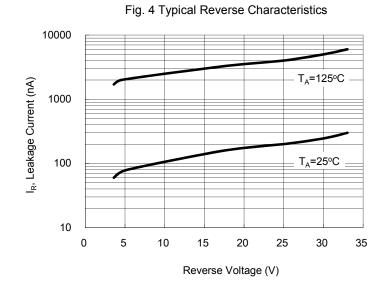
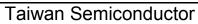


Fig. 2 Admissible Power Dissipation Curve 300 250 Powe Dissipation (mW) 200 150 100 50 50 0 20 40 60 80 100 120 140 Ambient Temperature (°C)









ORDERING INFORMATION					
PART NO.	PART NO.	PACKING	PACKING CODE	PACKAGE	PACKING
	SUFFIX (Note 1)	CODE	SUFFIX	PACKAGE	
RB751V-40WS -xx	RR	G	SOD-323F	3,000 / 7" Reel	
	R9	G		10,000 / 13" Reel	

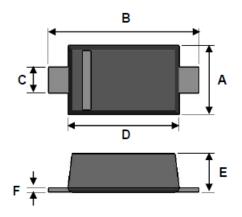
Note 1: Part No. Suffix "-xx " would be used for special requirement

EXAMPLE					
PREFERRED P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
RB751V-40WS RR	RB751V-40WS		RR		Multiple manufacture source
RB751V-40WS RRG	RB751V-40WS		RR	G	Multiple manufacture source Green compound
RB751V-40WS-B0 RRG	RB751V-40WS	-B0	RR	G	Define manufacture source Green compound



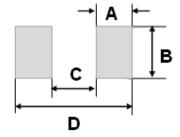
### PACKAGE OUTLINE DIMENSIONS

### **SOD-323F**



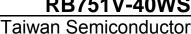
DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min	Max	Min	Max	
А	1.15	1.35	0.045	0.053	
В	2.30	2.80	0.091	0.110	
С	0.25	0.40	0.010	0.016	
D	1.60	1.80	0.063	0.071	
Е	0.80	1.10	0.031	0.043	
F	0.05	0.25	0.002	0.010	

### SUGGEST PAD LAYOUT



	Unit (mm)	Unit (inch)		
DIM.	Typ.	Тур.		
Α	0.63	0.025		
В	0.83	0.033		
С	1.60	0.063		
D	2.86	0.113		







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